

# SOT1104-1

plastic low profile fine-pitch ball grid array package; 135 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA135
<b>Package type industry code</b>	LFPGA135
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-8-2008

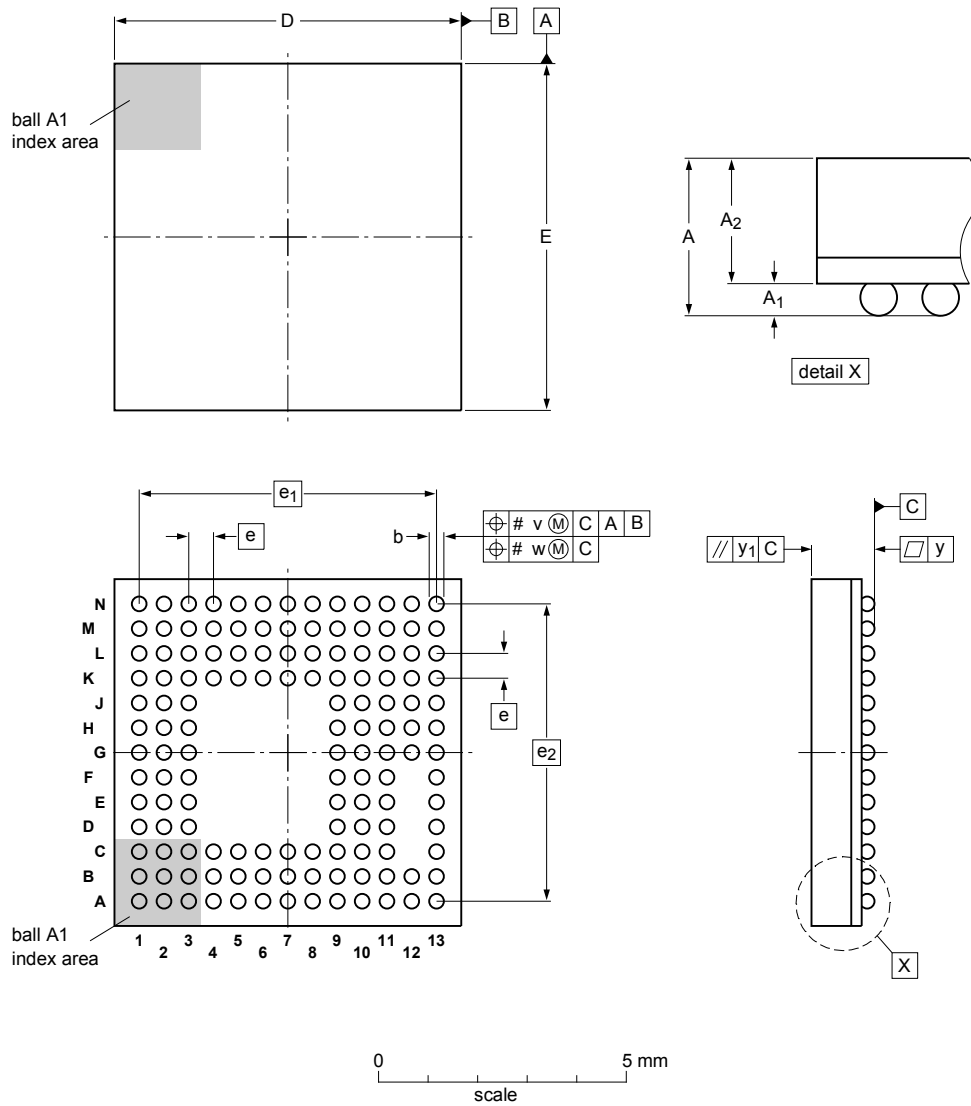
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1.15	-	1.26	1.4	mm
A <sub>2</sub>	package height	0.95	-	1.01	1.1	mm
n <sub>2</sub>	actual quantity of termination	-	-	135	-	



## 2. Package outline

LFBGA135: plastic low profile fine-pitch ball grid array package; 135 balls SOT1104-1



**DIMENSIONS** (mm are the original dimensions)

UNIT		A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	max	1.40	0.30	1.10	0.35	7.1	7.1	0.5	6	6	0.15	0.05	0.08	0.1
	nom	1.26	0.25	1.01	0.30	7.0	7.0							
	min	1.15	0.20	0.95	0.25	6.9	6.9							

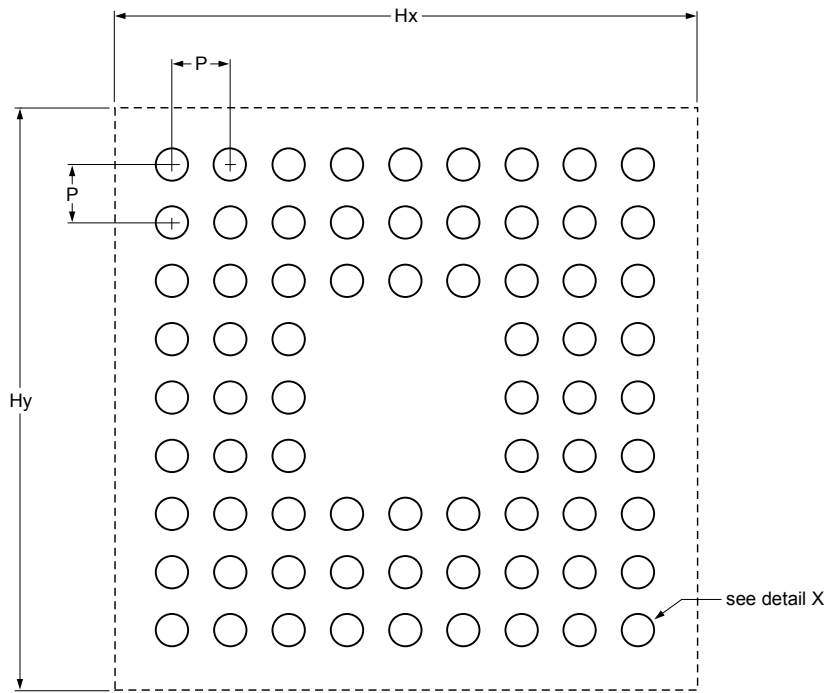
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1104-1		---	---			08-07-02 08-08-06

**Fig. 1. Package outline LFBGA135 (SOT1104-1)**

### 3. Soldering

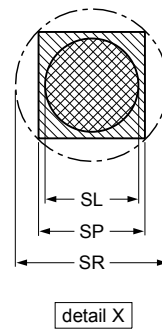
Footprint information for reflow soldering of LFBGA135 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	7.400	7.400

sot1104-1\_fr

Fig. 2. Reflow soldering footprint for LFBGA135 (SOT1104-1)

## 4. Legal information

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